





Design Rules Verification Report

Filename: C:\Users\matt\Other-Repos\sensor_module\sensor_to_uart\sensor_to_uart.PcbD

Warnings 0
Rule Violations 59

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=0.254mm) (All),(All)	
Short-Circuit Constraint (Allowed=No) (All),(All)	
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.254mm) (Max=0.8mm) (Preferred=0.254mm) (All)	
Power Plane Connect Rule(Relief Connect)(Expansion=0.508mm) (Conductor Width=0.254mm)	0
Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)	3
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	
Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)	46
Silk to Silk (Clearance=0.254mm) (All),(All)	
Net Antennae (Tolerance=0mm) (All)	
Room sensor_to_uart (Bounding Region = (102.5mm, 90mm, 152.5mm, 125.503mm)	
Height Constraint (Min=0mm) (Max=25.4mm) (Prefered=12.7mm) (All)	
Total	59

Clearance Constraint (Gap=0.254mm) (All),(All)

Clearance Constraint: (0.22mm < 0.254mm) Between Pad C1-1(13.225mm,26.375mm) on Top Layer And Pac Clearance Constraint: (0.22mm < 0.254mm) Between Pad C4-1(24.75mm,23.01mm) on Top Layer And Pac Clearance Constraint: (0.22mm < 0.254mm) Between Pad C5-1(24.75mm,20.74mm) on Top Layer And Pac

Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)

Hole Size Constraint: (3.2mm > 2.54mm) Pad J1-POS1(37.5mm,16.935mm) on Multi-Layer Actual Hole Size = 3.2mm
Hole Size Constraint: (3.2mm > 2.54mm) Pad J1-POS2(37.5mm,28.065mm) on Multi-Layer Actual Hole Size = 3.2mm
Hole Size Constraint: (3mm > 2.54mm) Pad J2-MNT(42.5mm,7.5mm) on Multi-Layer Actual Hole Size = 3mm

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)

Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C1-1(13.225mm,26.375mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C4-1(24.75mm,23.01mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C5-1(24.75mm,20.74mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.155mm < 0.254mm) Between Pad R7-1(23mm,20.95mm) on Top Layer And Via

Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All) Silk To Solder Mask Clearance Constraint: (0.175mm < 0.254mm) Between Pad C2-1(12.4mm,12.5mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.193mm < 0.254mm) Between Pad C2-1(12.4mm,12.5mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.175mm < 0.254mm) Between Pad C2-2(10.6mm,12.5mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.175mm < 0.254mm) Between Pad C2-2(10.6mm,12.5mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.175mm < 0.254mm) Between Pad C3-1(20.5mm,5.6mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.175mm < 0.254mm) Between Pad C3-1(20.5mm,5.6mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.175mm < 0.254mm) Between Pad C3-2(20.5mm,7.4mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.193mm < 0.254mm) Between Pad C3-2(20.5mm,7.4mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Pad J1-S1(34.45mm,14.75mm) on Multi-Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R1-1(22.75mm,26.95mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.216mm < 0.254mm) Between Pad R1-1(22.75mm,26.95mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R1-2(22.75mm,25.55mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R1-2(22.75mm,25.55mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R2-1(24.75mm,26.95mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.216mm < 0.254mm) Between Pad R2-1(24.75mm,26.95mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R2-2(24.75mm,25.55mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R2-2(24.75mm,25.55mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R3-1(22.75mm,24.2mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.216mm < 0.254mm) Between Pad R3-1(22.75mm,24.2mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R3-2(22.75mm,22.8mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R3-2(22.75mm,22.8mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R4-1(21.25mm,16.55mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R4-1(21.25mm,16.55mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R4-2(21.25mm,17.95mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.216mm < 0.254mm) Between Pad R4-2(21.25mm,17.95mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R5-1(23mm,16.55mm) on Top Layer And Trac Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R5-1(23mm,16.55mm) on Top Layer And Trac Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R5-2(23mm,17.95mm) on Top Layer And Trac Silk To Solder Mask Clearance Constraint: (0.216mm < 0.254mm) Between Pad R5-2(23mm,17.95mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R6-1(24.75mm,16.55mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R6-1(24.75mm,16.55mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R6-2(24.75mm,17.95mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.216mm < 0.254mm) Between Pad R6-2(24.75mm,17.95mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R7-1(23mm,20.95mm) on Top Layer And Trac Silk To Solder Mask Clearance Constraint: (0.216mm < 0.254mm) Between Pad R7-1(23mm,20.95mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R7-2(23mm,19.55mm) on Top Layer And Traci Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R7-2(23mm,19.55mm) on Top Layer And Trac Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R9-1(21.25mm,19.55mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R9-1(21.25mm,19.55mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad R9-2(21.25mm,20.95mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.216mm < 0.254mm) Between Pad R9-2(21.25mm,20.95mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.06mm < 0.254mm) Between Pad TP3-1(16.4mm,10.8mm) on Top Layer And Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad U2-1(16.4mm,4.2mm) on Top Layer And Trac Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad U2-2(16.4mm,6.5mm) on Top Layer And Trac Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad U2-3(16.4mm,8.8mm) on Top Layer And Trac Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Pad U2-4(10.6mm,6.5mm) on Top Layer And Trac

Silk to Silk (Clearance=0.254mm) (All),(All)

Electrical Rules Check Report

Class	Document	Message
Warning	sensor_to_uart.SchDoc	Net SENSOR_TX+ has no driving source (Pin J1-1, Pin R1-2, Pin R2-1, Pin
		U1-8)
Warning	sensor_to_uart.SchDoc	Net SENSOR_TX- has no driving source (Pin C4-1, Pin J1-2, Pin R3-1, Pin
		U1-7)
Warning	sensor_to_uart.SchDoc	Net USART1_TX has no driving source (Pin FTDI-3, Pin TP2-1, Pin U1-3)



